Product End-of-Life Disassembly Instructions

Product Category: Storage Enclosures
Marketing Name / Model [List multiple models if applicable.]
V-class
QR619A, HP 3PAR V 4x100GB 4G SSD Mag QR620A, HP 3PAR V 4x200GB 4G SSD Mag QR621A, HP 3PAR V 4x300GB 15K 4G Drive Mag QR622A, HP 3PAR V 4x600GB 15K 4G Drive Mag QR623A, HP 3PAR V 4x2TB 7.2K 4G Drive Mag QR624A, HP 3PAR V Upgr 4x100GB 4G SSD Mag QR625A, HP 3PAR V Upgr 4x200GB 4G SSD Mag QR626A, HP 3PAR V Upgr 4x300GB 15K 4G Drive Mag QR627A, HP 3PAR V Upgr 4x600GB 15K 4G Drive Mag QR628A, HP 3PAR V Upgr 4x2TB 7.2K 4G Drive Mag QR592A, HP 3PAR V Drive Chassis 40-Disk, 4G QR609A, HP 3PAR Upgr V Drv Chassis 40-Disk, 4G
T-Class
QL239B, HP 3PAR 4x300 GB 15K 4-Gb/sec FC LFF Drive Magazine QL242B, HP 3PAR 4x1 TB 4-Gb/sec FC LFF Nearline Drive Magazine QL251B, HP 3PAR 4x50 GB 4-Gb/sec SSD Magazine QL252B, HP 3PAR 4x600 GB 15K 4-Gb/sec FC LFF Drive Magazine QL235B, HP 3PAR Drive Chassis HP 3PAR 40-disk 4 Gb/sec Drive Chassis QL313B, HP 3PAR Upgrade 40-Disk 4 Gb/sec Drive Chassis QL317B, HP 3PAR Upgrade 4x300 GB 15K 4-Gb/sec FC LFF Drive Magazine QL320B, HP 3PAR Upgrade 4x1 TB 4-Gb/sec FC LFF Nearline Drive Magazine QL335B, HP 3PAR Upgrade 4x50 GB 4-Gb/sec SSD Magazine QL336B, HP 3PAR Upgrade 4x600 GB 15K 4-Gb/sec FC LFF Drive Magazine QL339B, HP 3PAR Upgrade 4x2 TB 4-Gb/sec FC LFF Nearline Drive Magazine QR612B, HP 3PAR 4x100 GB 4-Gb/sec SSD Magazine QR614B, HP 3PAR 4x200 GB 4-Gb/sec SSD Magazine QR616B, HP 3PAR Upgrade 4x100 GB 4-Gb/sec SSD Magazine QR618B, HP 3PAR Upgrade 4x200 GB 4-Gb/sec SSD Magazine

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product

PSG instructions for this template are available at EL-MF877-01

Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	Min Config: 23 Max Config: 63
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		4
External electrical cables and cords		4
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw Driver, phillips (+ driver)	#2
Screw Driver, phillips (+ driver)	#1
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

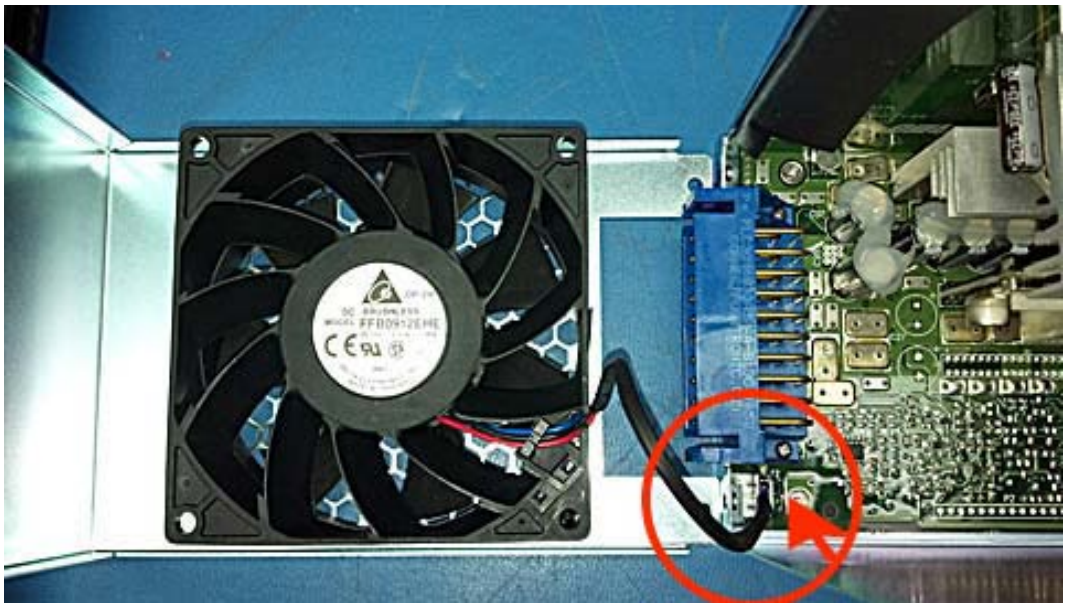
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove power supplies from
2. Remove the Fcal PCBA Assy
3. Remove the Midplane from Chassis
4. Remove the Drive Sled PCBA
5.
6.

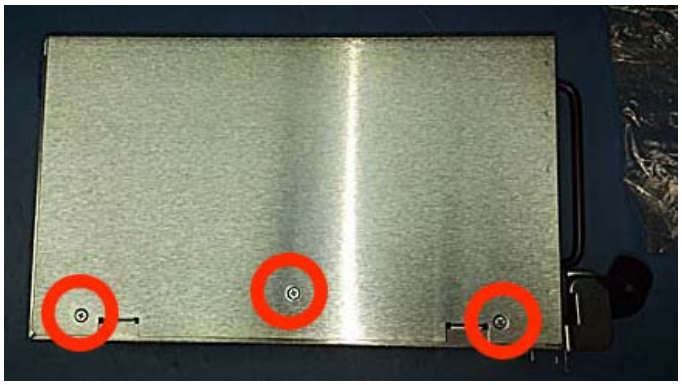
7.
8.
9.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Disassembling MBOD Power Supplies (PS):
Remove two screws on front side and rear of the power supply and remove the top cover.       
Disconnect fan connector to remove the cover w/ fan.



Remove six screws from bottom, and three screws on the side.



Lift up the bottom PCBA and slide the 2 PCBA assy away from the Front Fan Assembly

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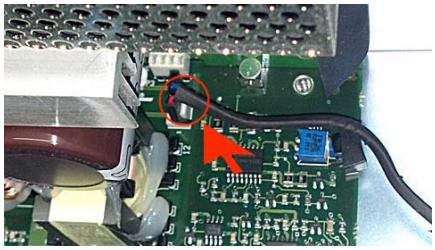
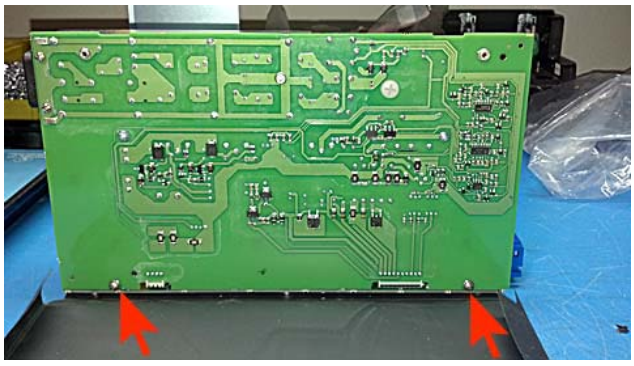
Disconnect the Front Fan Connector

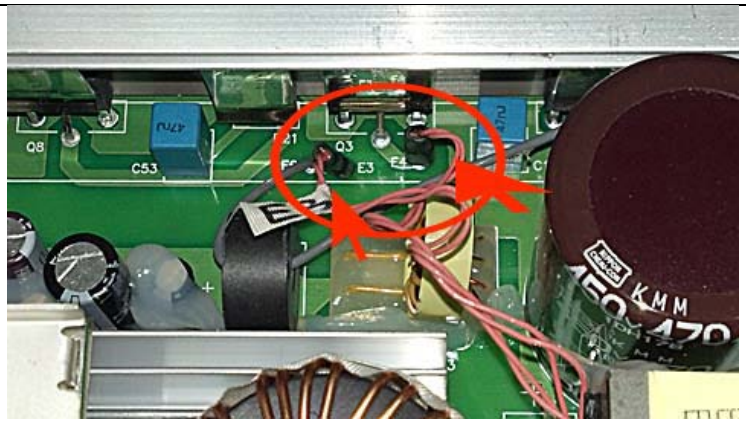


Slide out the 2 PCBA Assy from the Chassis

Remove two screws from the right PCBA



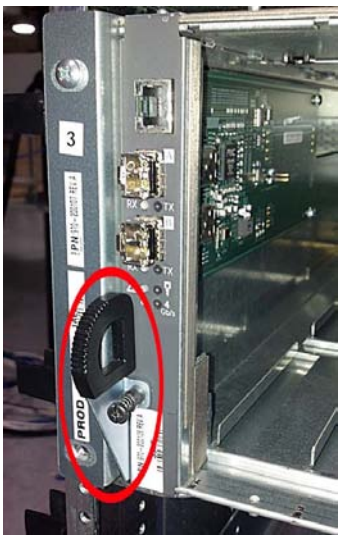
Slide the PCBA up and disconnect the Board wires



Remove the Capacitor

Disassembling MBOD FCAL PCBA:

Loosen the mounting screw in front of the FCAL PCBA assy, pivot the handle and slide out the assy:



Remove screws holding the PCBA:

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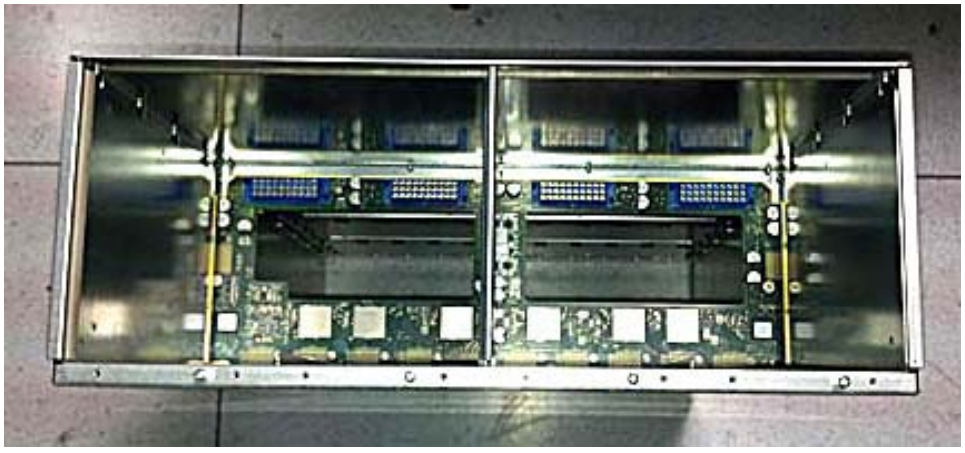
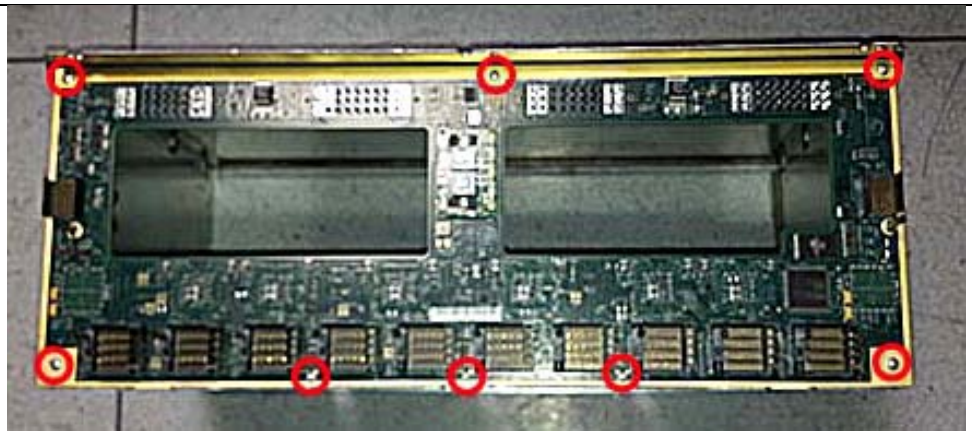
Disassembling MBOD Midplane:

Loosen the four screws as shown:

Pull out the cage assembly holding the PCBA from the main Chassis:

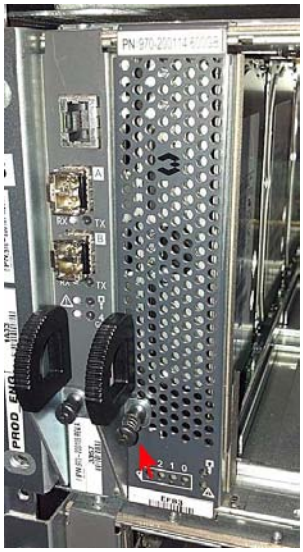


Remove the eight screws holding the Midplane PCBA:

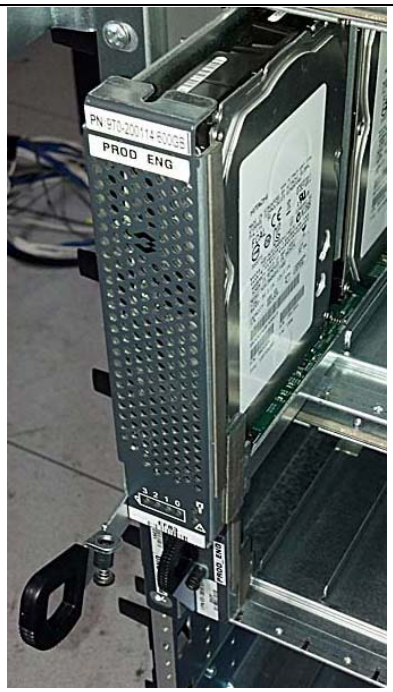


Disassembling MBOD Drive Sled PCBA and HDDs:

Loosen the mounting screw in front of the Drive Mag assy,

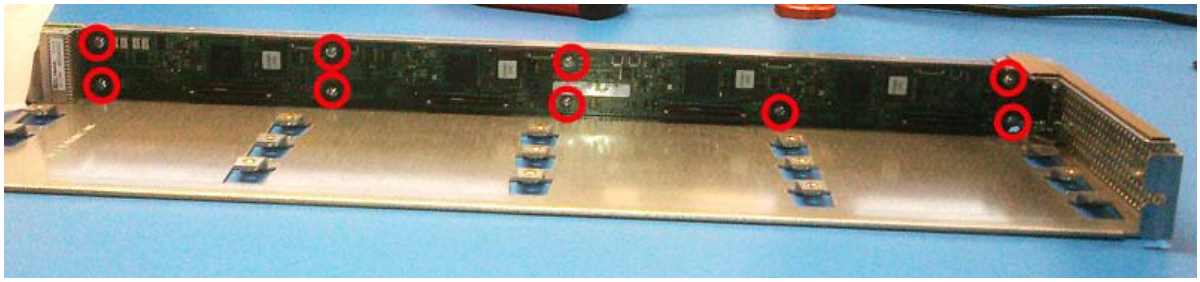


Pivot the handle downward and slide out the Dmag assy:



Remove screws holding each of the drive assemblies, and slide the HDD away from the connector to remove Hard Drive.

Remove the 9 screws holding the Sled PCBA and remove it.



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